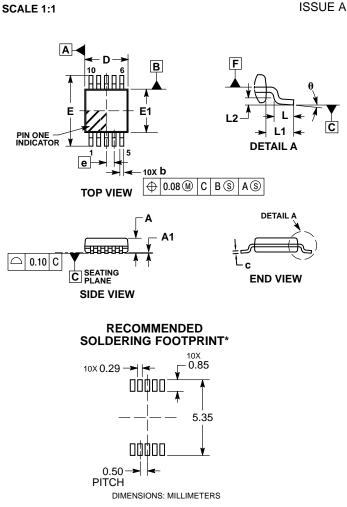
DATE 20 JUN 2017





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

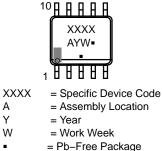
NOTES:

MSOP10, 3x3 CASE 846AE

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSIONS: MILLIMETERS. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN 1. 2. 3
- 4
- ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN EXCESS OF MAXIMUM MATERIAL CONDITION. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. DIMENSIONS D AND E ADE DETERMINED AT DATIME DIMENSIONS D AND E ARE DETERMINED AT DATUM F. DATUMS A AND B TO BE DETERMINED AT DATUM F.
- 5.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE 6 BODY.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			1.10	
A1	0.00	0.05	0.15	
A2	0.75	0.85	0.95	
b	0.17		0.27	
С	0.13		0.23	
D	2.90	3.00	3.10	
Е	4.75	4.90	5.05	
E1	2.90	3.00	3.10	
е	0.50 BSC			
L	0.40	0.70	0.80	
L1	0.95 REF			
L2	0.25 BSC			
θ	0°		8°	

GENERIC **MARKING DIAGRAM***



А

Y

W

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present and may be in either location. Some products may not follow the Generic Marking.

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DESCRIPTION:	MSOP10, 3X3	PAGE 1 OF	2



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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM POD #MSOP10-013-01 TO ON SEMICON- DUCTOR. REQ. BY B. BERGMAN.	19 DEC 2008
A	MODIFIED DRAWING TO ON SEMICONDUCTOR JEDEC STANDARD AND ADDED SOLDERING FOOTPRINT. REQ. BY M. PREJZEK.	20 JUN 2017

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